

REMARKS

Favorable reconsideration of this application is respectfully requested in view of the previous amendments and the following remarks.

At the outset, the Examiner is, once again, kindly asked to make U.S. Patent No. 6,159,770, hereinafter Tetaka, officially of record via citation on a copy of Form PTO-892. This document has been repeatedly discussed by the Examiner but has not been formally cited. Should the Examiner believe that Tetaka has already been made of official record, Applicants respectfully request that the Examiner specifically point out the paper in which Tetaka is believed to have been formally cited.

The Examiner again rejects Claim 1, the only non-withdrawn independent claim, based on the disclosures in U.S. Patent No. 6,744,634, hereinafter Yen, in view of Tetaka.

Claim 1 recites a method for manufacturing a USB electronic key, including cutting out a microcircuit from a tape having a plurality of microcircuits, each microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, the method further including, in a single operation, adjusting the thickness of the microcircuit at least in the area of the contact pads, so as to have a thickness that conforms to the USB Standard.

The Official Action correctly notes that Yen does not disclose cutting out a microcircuit from a tape having a plurality of microcircuits. However, in section "5" of the Official Action, the Examiner maintains that Tetaka discloses cutting out a microcircuit from a tape having a plurality of microcircuits, and points to Tetaka's disclosures of using a laser generating apparatus, a rotary cutter, a break-away tool, or a push-up tool. However, in none of these processes is the resin package 412 cut

out from the adhesive tape 463. As discussed in lines 22-43 of column 60 of Tetaka, the laser generating apparatus 484 and the rotary cutter 496 are used instead for breaking the resin packages 412 from gate portions 432. Moreover, as discussed from line 54 of column 61 through line 37 of column 62 of Tetaka, the break-away tool 491 and the push-up tool 496 are used to separate the resin packages 412 from the adhesive tape 463, but not to cut the resin packages 412 out from the adhesive tape 463. Indeed, as Tetaka's resin packages 412 are simply attached to the adhesive tape 463, rather than forming part of the adhesive tape 463, it is not possible to cut the resin packages 412 out from the adhesive tape 463. Instead, Tetaka's resin packages 412 are simply separated from the adhesive tape 463 by one of the methods discussed above.

Claim 1 is therefore allowable over Yen in view of Tetaka, and withdrawal of the rejection of Claim 1 is respectfully requested.

New Claim 15 recites a method for manufacturing a USB electronic key, including cutting out, from a tape having a plurality of microcircuits, a portion of the tape including one of the microcircuits, each microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads; the method further including, in a single operation, adjusting the thickness of the cut-out portion of the tape including the one of the microcircuits at least in the area of the contact pads of the one of the microcircuits, so as to have a thickness that conforms to the USB Standard. New Claim 15 is also allowable over Yen in view of Tetaka. For example, neither Yen nor Tetaka disclose cutting out, from a tape having a plurality of microcircuits, a portion of the tape including one of the microcircuits.

The dependent claims are allowable at least by virtue of their dependence from allowable independent Claim 1. Thus, a detailed discussion of the additional distinguishing features recited in the dependent claims is not set forth at this time.

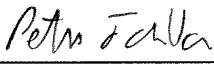
Early and favorable action with respect to this application is respectfully requested.

Should any questions arise in connection with this application or should the Examiner believe that a telephone conference with the undersigned would be helpful in resolving any remaining issues pertaining to this application, the undersigned respectfully requests that he be contacted at the number indicated below.

Respectfully submitted,

BUCHANAN INGERSOLL & ROONEY PC

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By: 
Peter T. deVore
Registration No. 60361

P.O. Box 1404
Alexandria, VA 22313-1404
703 836 6620